

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: NAKAMURA, et al.  
Serial No.: 10/500,119  
Filed: June 17, 2005  
For: CONNECTION BOARD, AND MULTI-LAYER WIRING BOARD,  
SUBSTRATE FOR SEMICONDUCTOR PACKAGE AND  
SEMICONDUCTOR PACKAGE USING CONNECTION  
BOARD, AND MANUFACTURING METHOD THEREOF  
Group AU: 2841  
Examiner: Ishwarbhai B Patel  
Confirm. No: 7910

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

June 5, 2007

Sir:

In response to the Office Action mailed March 5, 2007, please amend the  
above-identified application as listed in the following, and as set forth on the  
following pages:

**Amendments to the Claims; and**

**Remarks** are included following the amendments.